Visual Inspection services
The purposes

Improve the quality of CMP services
Observe and check the incoming and the outgoing dies
Provide a detailed summary of the observation
Provide High quality photos of customers projects (on request).
High quality photos
24.2 Mpx CMOS Sensor

1.9x1.9 mm die packaged in CQFP (Wirebond)

Die packaged in DIL(Wirebond)

Die with SolderBumps
Issues Identification

Cracks on die edges

Scratches

Impurities
The observation bench

A precise camera for die scale picturing

An optical microscope for inspection (pads, die edges, potential impurities...).

A hood which produces a vertical laminar flow of clean air (ISO Class 3 air quality environment).
Observation Report

Visual observations

User’s address

Visual Inspection sheet

Circuit size: 1955 x 1955 µm
Circuit thickness: 250µm

Ordered die: 25
Packaged die: 6 + 1 set up
Package type: CQFP44

Observations:
- No impurities on the pads have been observed.
- No sawing projections on the passivation have been observed.
- Chip edges are clean after slicing.
- The steps of the CMP are good.
- Bonding wires are fine.

Die edges inspection. (Checking if the sawing is clean.)
Thanks for your attention!